

REMARKS

Claims 1-5 and 29 are now pending in the application. The Examiner asserts that the present application includes product by process claims. Although not addressed herein, Applicant respectfully disagrees with this assertion. In any event, the Examiner is respectfully requested to reconsider and withdraw the rejections in view of remarks contained herein.

REJECTION UNDER 35 U.S.C. § 103

Claims 1, 2, 4, 5 and 29 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 6,255,741 (Yoshihara) or an equivalent, Japanese Patent No. 2000-31349. This rejection is respectfully traversed.

Yoshihara does not constitute prior art in relation to the present application in accordance with 35 U.S.C. 103(c). Yoshihara qualifies as a prior art reference under 35 U.S.C. 102(e). However, Applicant hereby asserts that the subject matter of the present application and Yoshihara were, at the time the invention was made, under an obligation to be assigned to the same entity, Denso Corporation. Applicant also notes that the publication of the Japanese equivalent patent document is not prior art in relation to the present application. Accordingly, Applicant respectfully requests reconsideration and withdrawal of this rejection.

Claims 1, 2, 4, 5 and 29 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 6,824,177 (Yoshihara) or an equivalent, Japanese Patent No. 9-27466. This rejection is respectfully traversed.

Yoshihara is directed generally to a method for manufacturing a semiconductor device. Of interest, Yoshihara discloses an adhesive sheet 2 which covers the surface of a semiconductor wafer 1 as shown in Figure 4A. However, the adhesive force of the adhesive material appears to be uniform across the entire surface of the adhesive sheet. In other words, Yoshihara does not teach or suggest a specific region of the adhesive portion having a less adhesive characteristic than a vicinal region surrounding the specific region.

Applicant's claimed invention is similarly directed to a semiconductor device. However, Claim 1 recites that "the adhesive portion having a specific region having an adhesion smaller than that of a vicinal region of the adhesive portion surrounding the specific region". Therefore, it is respectfully submitted that Claim 1, along with the claims depending therefrom, are patentability distinct over Yoshihara. Accordingly, Applicant respectfully requests reconsideration and withdrawal of this rejection.

ALLOWABLE SUBJECT MATTER

The Examiner states that claim 3 would be allowable if rewritten in independent form. Applicant respectfully acknowledges the Examiner's indication of the allowable claim, but elects to defer rewriting the objected to claim until the Examiner has considered Applicant's arguments.

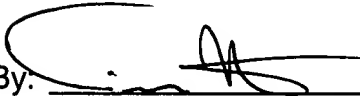
CONCLUSION

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action, and as such, the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication

will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

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